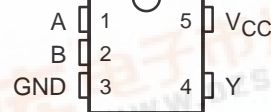
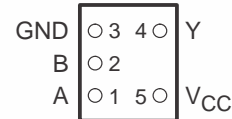


- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 2.5 ns at 1.8 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 8 -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE
(TOP VIEW)YEA OR YZA PACKAGE
(BOTTOM VIEW)

description/ordering information

This single 2-input exclusive-OR gate is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUC1G86 performs the Boolean function $Y = A \oplus B$ or $Y = \bar{A}B + A\bar{B}$ in positive logic.

A common application is as a true/complement element. If the input is low, the other input is reproduced in true form at the output. If the input is high, the signal on the other input is reproduced inverted at the output.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
–40°C to 85°C	NanoStar™ WCSP (DSBGA) – YEA	Tape and reel	SN74AUC1G86YEAR	— _UH_
	NanoFree™ WCSP (DSBGA) – YZA (Pb-free)	Tape and reel	SN74AUC1G86YZAR	
	SOT (SOT-23) – DBV	Tape and reel	SN74AUC1G86DBVR	U86_
	SOT (SC-70) – DCK	Tape and reel	SN74AUC1G86DCKR	UH_

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN74AUC1G86

SINGLE 2-INPUT EXCLUSIVE-OR GATE

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FUNCTION TABLE

INPUTS		OUTPUT
A	B	
L	L	L
L	H	H
H	L	H
H	H	L

exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an SN74AUC1G86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



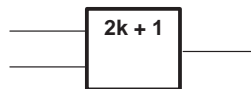
The output is active (low) if all inputs stand at the same logic level (i.e., $A = B$).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 3.6 V
Input voltage range, V_I (see Note 1)	−0.5 V to 3.6 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	−0.5 V to 3.6 V
Output voltage range, V_O (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Output clamp current, I_{OK} ($V_O < 0$)	−50 mA
Continuous output current, I_O	±20 mA
Continuous current through V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DBV package	206°C/W
DCK package	252°C/W
YEA/YZA package	154°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:

1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

SN74AUC1G86

SINGLE 2-INPUT EXCLUSIVE-OR GATE

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recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	0.8	2.7	V
V_{IH}	High-level input voltage	$V_{CC} = 0.8\text{ V}$	V_{CC}	V
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
V_{IL}	Low-level input voltage	$V_{CC} = 0.8\text{ V}$	0	V
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
V_I	Input voltage	0	3.6	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 0.8\text{ V}$	–0.7	mA
		$V_{CC} = 1.1\text{ V}$	–3	
		$V_{CC} = 1.4\text{ V}$	–5	
		$V_{CC} = 1.65\text{ V}$	–8	
		$V_{CC} = 2.3\text{ V}$	–9	
I_{OL}	Low-level output current	$V_{CC} = 0.8\text{ V}$	0.7	mA
		$V_{CC} = 1.1\text{ V}$	3	
		$V_{CC} = 1.4\text{ V}$	5	
		$V_{CC} = 1.65\text{ V}$	8	
		$V_{CC} = 2.3\text{ V}$	9	
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}	$I_{OH} = -100\text{ }\mu\text{A}$	0.8 V to 2.7 V	$V_{CC}-0.1$			V
	$I_{OH} = -0.7\text{ mA}$	0.8 V		0.55		
	$I_{OH} = -3\text{ mA}$	1.1 V	0.8			
	$I_{OH} = -5\text{ mA}$	1.4 V	1			
	$I_{OH} = -8\text{ mA}$	1.65 V	1.2			
	$I_{OH} = -9\text{ mA}$	2.3 V	1.8			
V_{OL}	$I_{OL} = 100\text{ }\mu\text{A}$	0.8 V to 2.7 V			0.2	V
	$I_{OL} = 0.7\text{ mA}$	0.8 V		0.25		
	$I_{OL} = 3\text{ mA}$	1.1 V			0.3	
	$I_{OL} = 5\text{ mA}$	1.4 V			0.4	
	$I_{OL} = 8\text{ mA}$	1.65 V			0.45	
	$I_{OL} = 9\text{ mA}$	2.3 V			0.6	
I_I	A or B input	$V_I = V_{CC}$ or GND	0 to 2.7 V		± 5	μA
I_{off}	V_I or $V_O = 2.7\text{ V}$		0		± 10	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	0.8 V to 2.7 V			10	μA
C_i	$V_I = V_{CC}$ or GND	2.5 V		2.5		pF

† All typical values are at $T_A = 25^\circ\text{C}$.

SN74AUC1G86

SINGLE 2-INPUT EXCLUSIVE-OR GATE

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switching characteristics over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$		$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$			$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	5.5	0.8	3.8	0.5	2.6	0.4	1	1.7	0.3	1.3	ns
	B		5	0.8	3.8	0.5	2.6	0.4	1	1.7	0.3	1.2	

switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$			$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8	1.5	2.6	0.7	2	ns
	B		0.8	1.5	2.6	0.7	2	

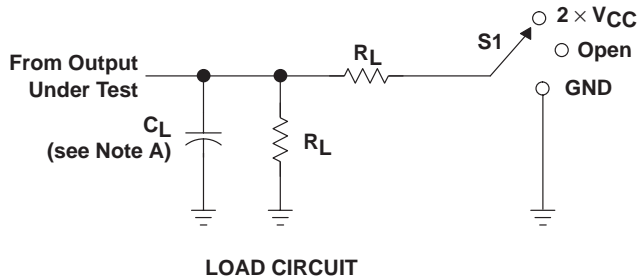
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$	$V_{CC} = 1.5 \text{ V}$	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	UNIT
			TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	$f = 10 \text{ MHz}$	16	16	16.5	17	18.5	pF

SN74AUC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

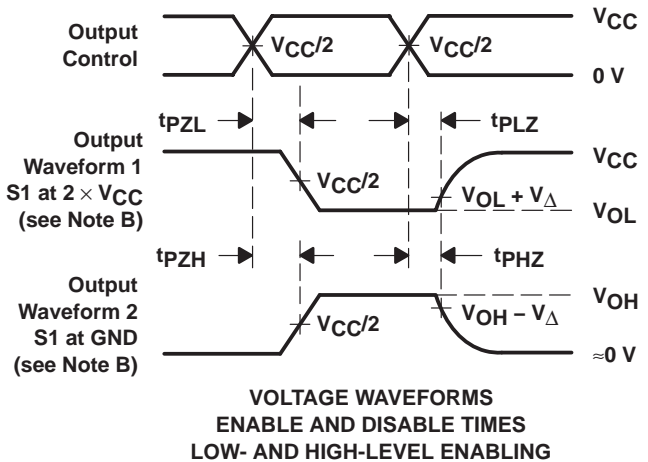
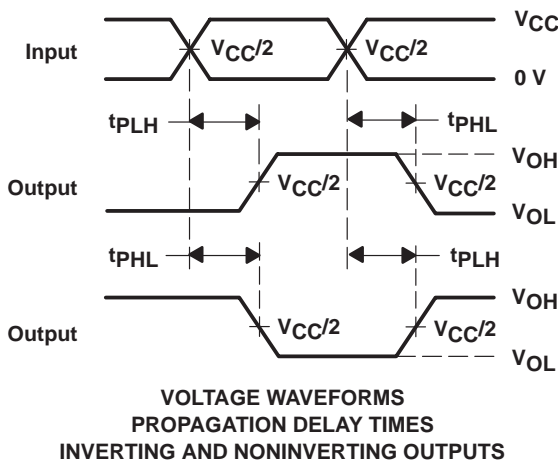
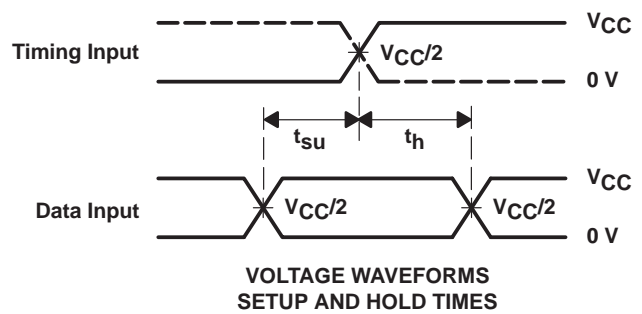
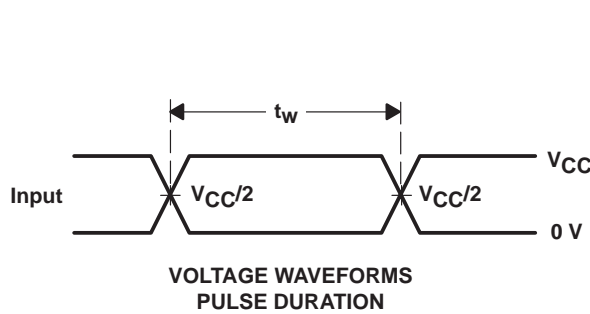
SCES389G – MARCH 2002 – REVISED FEBRUARY 2004

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

V_{CC}	C_L	R_L	V_{Δ}
0.8 V	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	15 pF	2 k Ω	0.15 V
1.8 V \pm 0.15 V	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	30 pF	500 Ω	0.15 V



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, slew rate \geq 1 V/ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUC1G86DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUC1G86DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUC1G86YEAR	ACTIVE	WCSP	YEA	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74AUC1G86YEPR	ACTIVE	WCSP	YEP	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74AUC1G86YZAR	ACTIVE	WCSP	YZA	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74AUC1G86YZPR	ACTIVE	WCSP	YZP	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

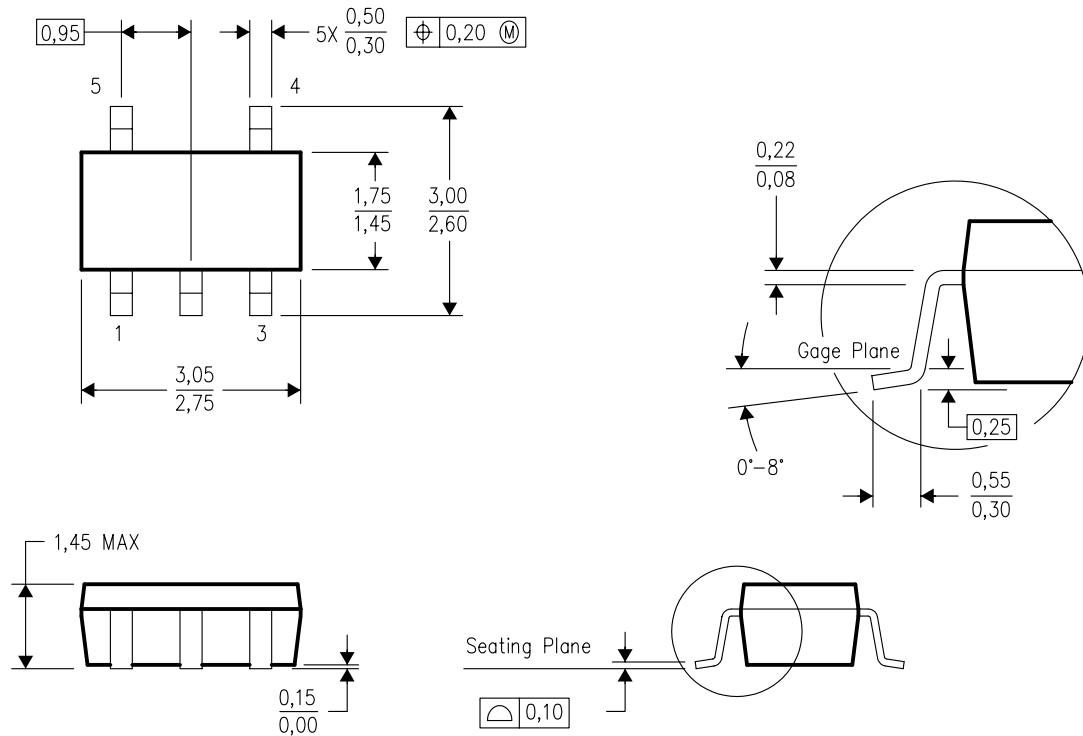
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MECHANICAL DATA

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4073253-4/1 04/2005

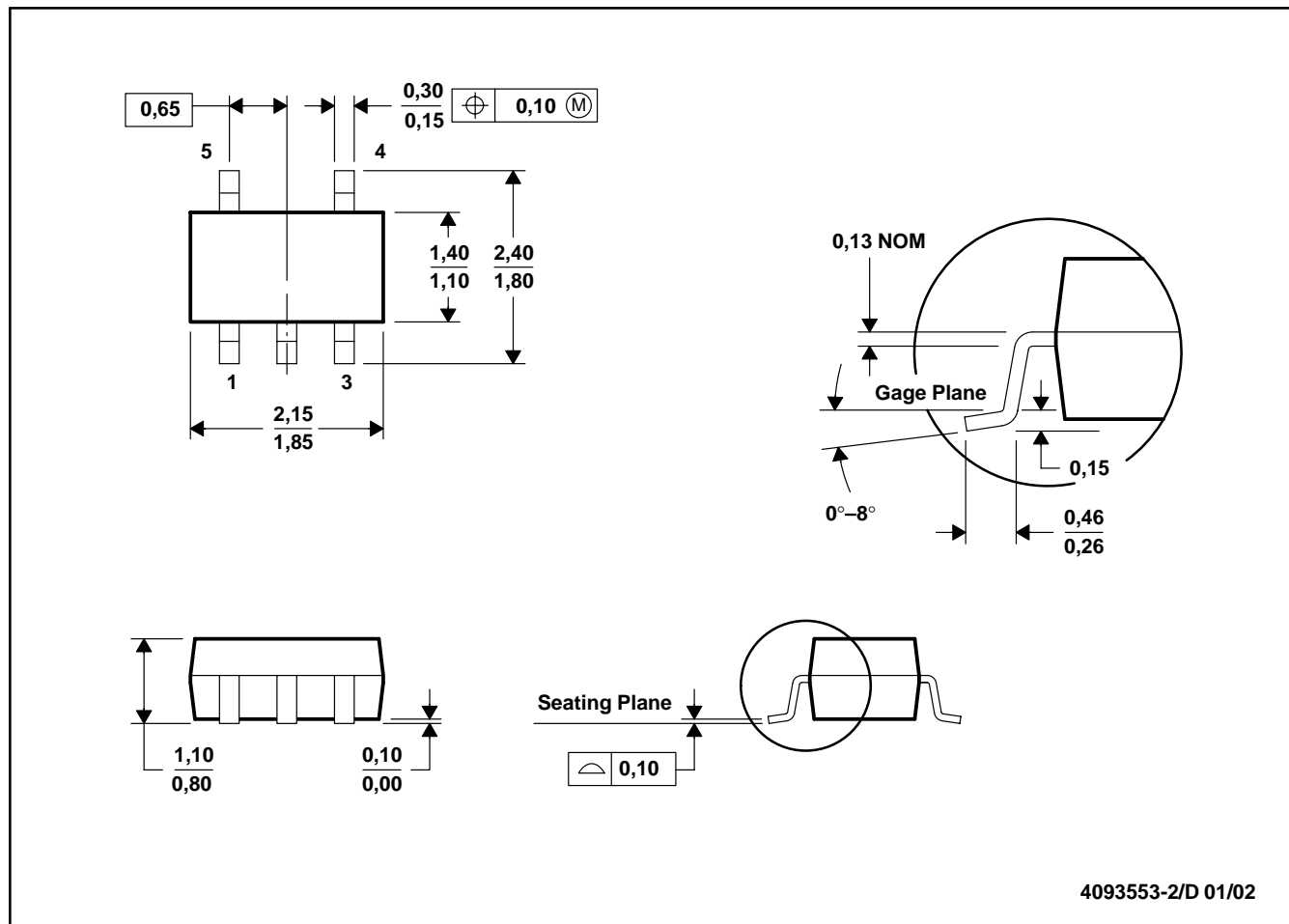
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-178 Variation AA.

MECHANICAL DATA

MPDS025C – FEBRUARY 1997 – REVISED FEBRUARY 2002

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

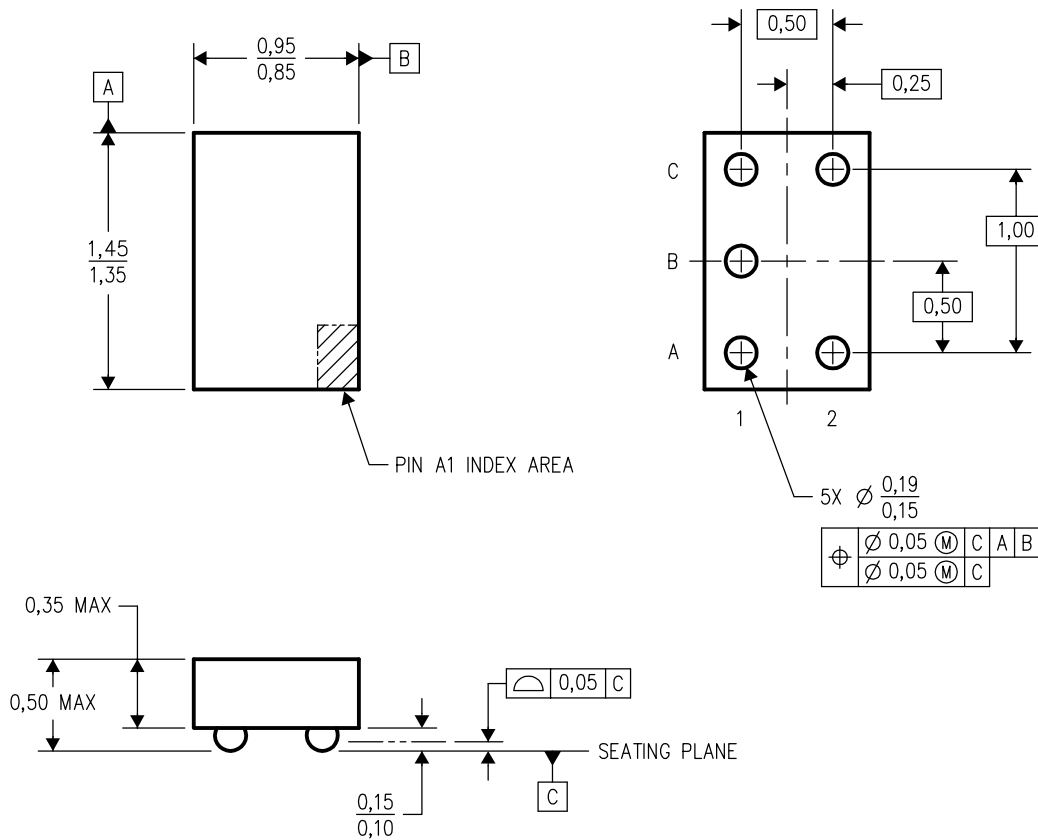


- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-203

MECHANICAL DATA

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4203167-2/C 04/2002

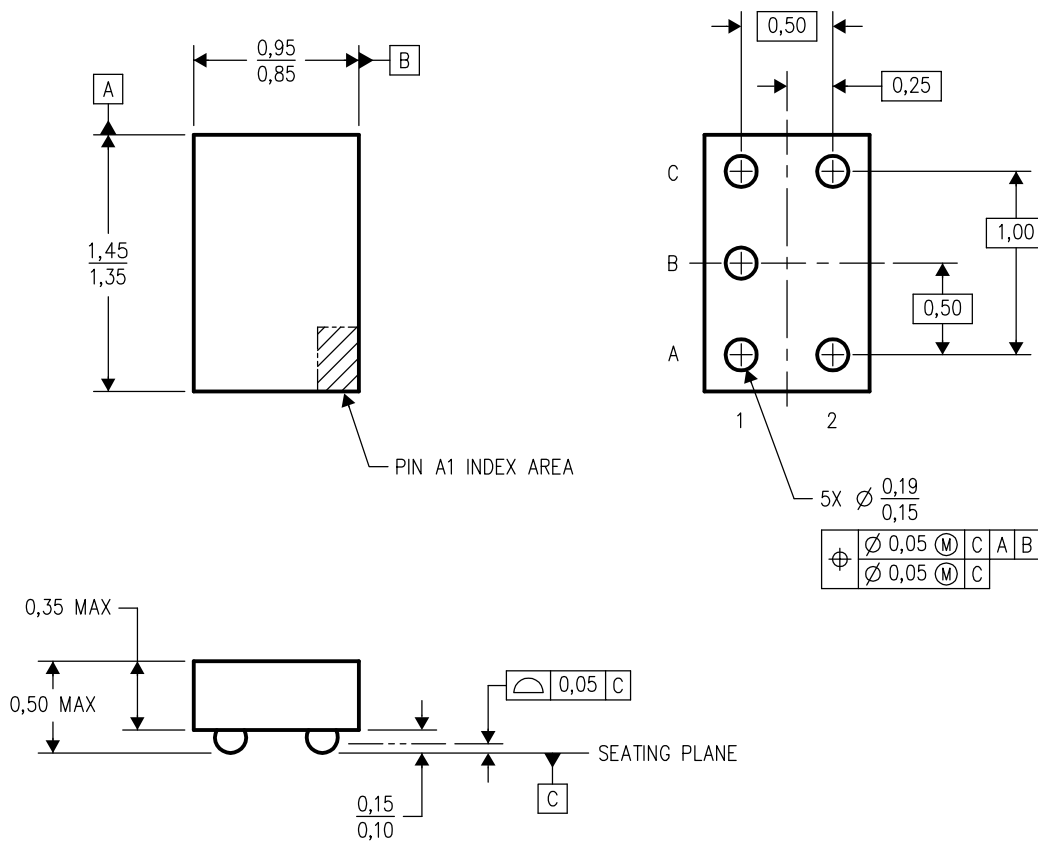
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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MECHANICAL DATA

YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204151-2/B 03/2002

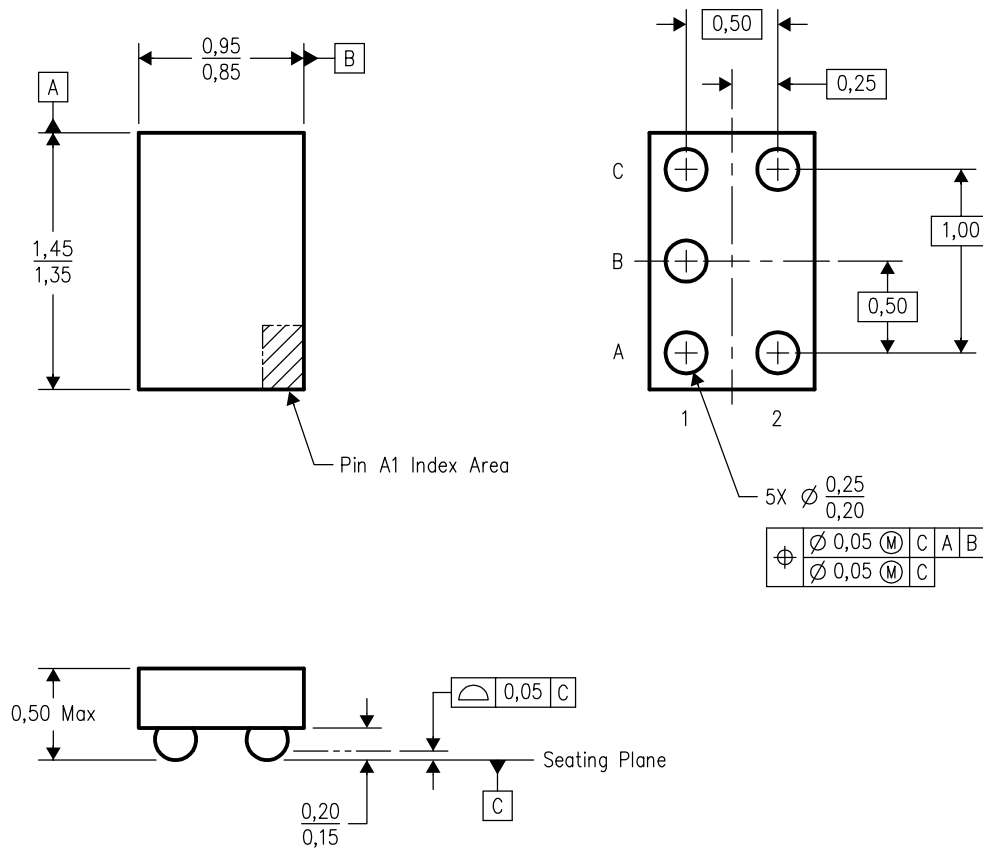
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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MECHANICAL DATA

YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204741-2/A 10/2002

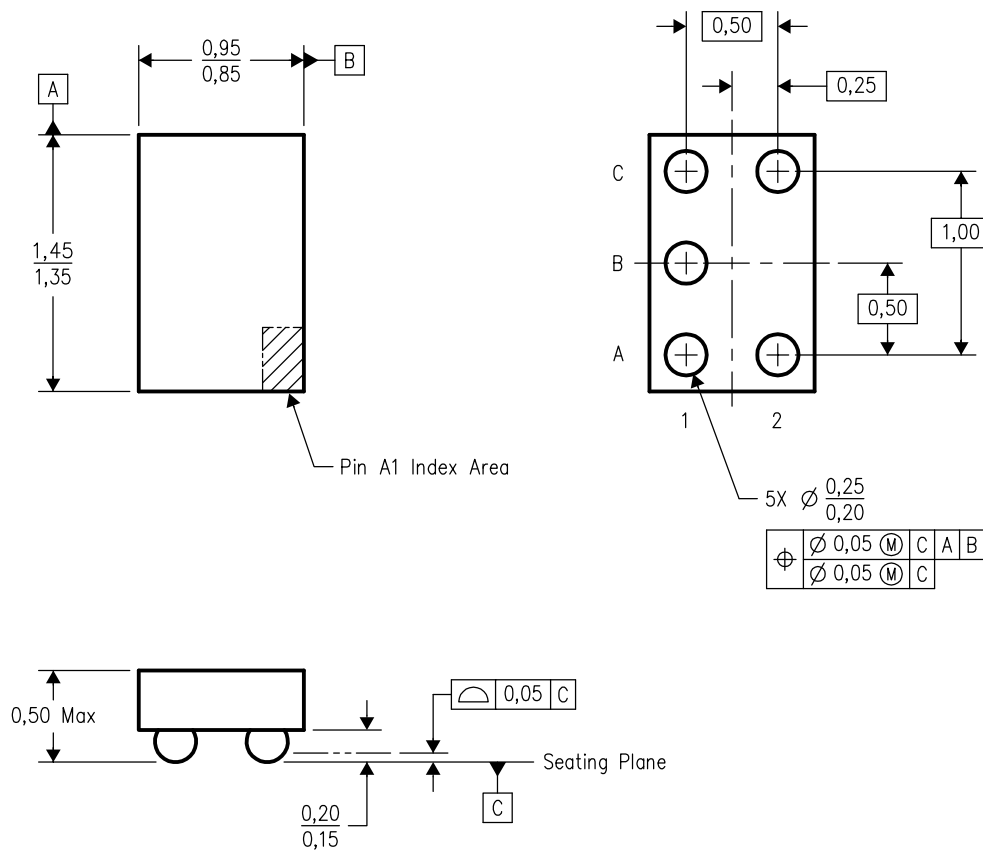
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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MECHANICAL DATA

YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204725-2/A 10/2002

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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